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Field Device Integration (FDI) - Part 6: FDI Technology Mapping

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

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**Field Device Integration (FDI) - Part 6: FDI Technology Mapping
(IEC 62769-6:2015)**

Intégration des appareils de terrain (FDI) - Partie 6:
Mapping de technologies FDI
(IEC 62769-6:2015)

Feldgeräteintegration (FDI) - Teil 6:
Technologieabbildungen
(IEC 62769-6:2015)

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European foreword

The text of document 65E/349/CDV, future edition 1 of IEC 62769-6, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62769-6:2015.

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Annex ZA (normative)

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NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804	series	Function Blocks (FB) for process control	EN 61804	series
IEC 62541	series	OPC unified architecture	EN 62541	series
IEC 62769-1	-	Devices and integration in enterprise systems; Field Device Integration - Part 1: Overview	-	-
IEC 62769-2	-	Devices and integration in enterprise systems; Field Device Integration - Part 2: FDI Client	-	-
IEC 62769-4	-	Devices and integration in enterprise systems; Field Device Integration - Part 4: FDI Packages	-	-
IEC 62769-5	-	Devices and integration in enterprise systems; Field Device Integration - Part 5: FDI Information Model	-	-
ISO/IEC 19505-1	-	Information technology - Object Management Group Unified Modeling Language (OMG UML) - Part 1: Infrastructure	-	-
ISO/IEC 29500	series	Information technology - Document description and processing languages - Office Open XML File Formats	-	series



INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI) –
Part 6: FDI Technology Mapping**

**Intégration des appareils de terrain (FDI) –
Partie 6: Mapping de technologies FDI**





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INTERNATIONAL STANDARD

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**Field Device Integration (FDI) –
Part 6: FDI Technology Mapping**

**Intégration des appareils de terrain (FDI) –
Partie 6: Mapping de technologies FDI**

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/349/CDV	65E/426/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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- b) Method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) Methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
- d) Extensible Device Object Model, see Patent Family US12/893,680.

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FIELD DEVICE INTEGRATION (FDI) –

Part 6: FDI Technology Mapping

1 Scope

This part of IEC 62769 specifies the technology mapping for the concepts described in the Field Device Integration (FDI) standard. The technology mapping focuses on implementation regarding the components FDI Client and User Interface Plug-in (UIP) that are specific only to the workstation platform as defined in IEC 62769-4:2015, Annex E.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62541 (all parts), *OPC Unified Architecture*

IEC 61804 (all parts), *Function blocks (FB) for process control*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

NOTE IEC 62769-1 is technically identical to FDI-2021.

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technically identical to FDI-2022.

NOTE 2 IEC 62769-2 is technically identical to FDI-2023.

IEC 62769-4:2015, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 1 IEC 62769-5 is technically identical to FDI-2025.

NOTE 2 IEC 62769-5 is technically identical to FDI-2027.

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